
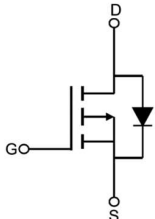


Description

Features <ul style="list-style-type: none"> ● -20V, -7A ● $R_{DS(ON)} < 24.5m\Omega$ @ $V_{GS} = -4.5V$ ● $R_{DS(ON)} < 32m\Omega$ @ $V_{GS} = -2.5V$ ● Advanced Trench Technology ● Provide Excellent $R_{DS(ON)}$ and Low Gate Charge ● Lead free product is acquired 	Application <ul style="list-style-type: none"> ● Load Switch ● PWM Application ● Power management
 <p>SOT-23-3</p>	 <p>Schematic Diagram</p>

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
VSM210P02A-S2	VSM210P02A	TAPING	SOT-23-3	7inch	3000	180000

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		±12	V
I _D	Continuous Drain Current	T _A = 25°C	-7	A
		T _A = 100°C	-4.6	A
I _{DM}	Pulsed Drain Current ^{note1}		-28	A
P _D	Power Dissipation	T _A = 25°C	2	W
R _{θJA}	Thermal Resistance, Junction to Ambient		62.5	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C

Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -20V, V _{GS} =0V,	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D = -250μA	-0.4	-0.7	-1.0	V
R _{DS(on)}	Static Drain-Source on-Resistance <small>note2</small>	V _{GS} = -4.5V, I _D = -7A	-	18.7	24.5	mΩ
		V _{GS} = -2.5V, I _D = -5A	-	22.7	32	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -10V, V _{GS} =0V, f=1.0MHz	-	2000	-	pF
C _{oss}	Output Capacitance		-	242	-	pF
C _{rss}	Reverse Transfer Capacitance		-	231	-	pF
Q _g	Total Gate Charge	V _{DS} = -10V, I _D = -3A, V _{GS} = -4.5V	-	15.3	-	nC
Q _{gs}	Gate-Source Charge		-	2.2	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	4.4	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -10V, I _D = -7A, V _{GS} = -4.5V, R _{GEN} =2.5Ω	-	10	-	ns
t _r	Turn-on Rise Time		-	31	-	ns
t _{d(off)}	Turn-off Delay Time		-	28	-	ns
t _f	Turn-off Fall Time		-	8	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-7	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-28	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = -7A	-	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

Typical Performance Characteristics

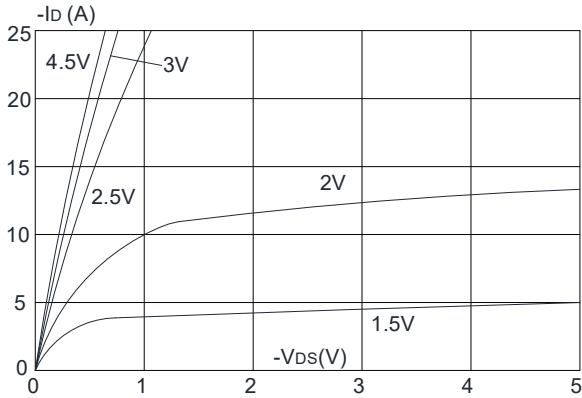
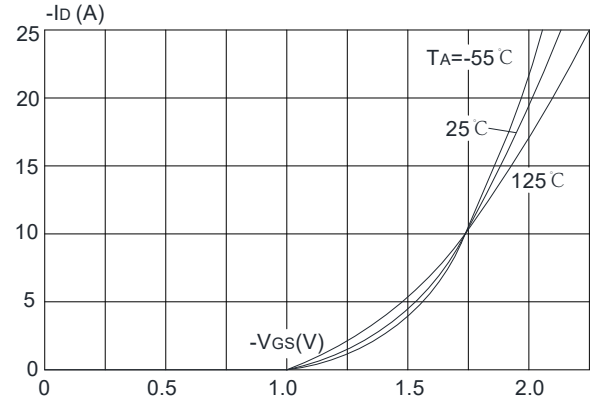
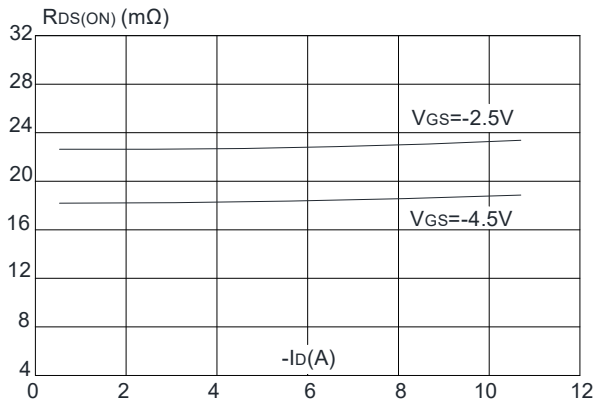
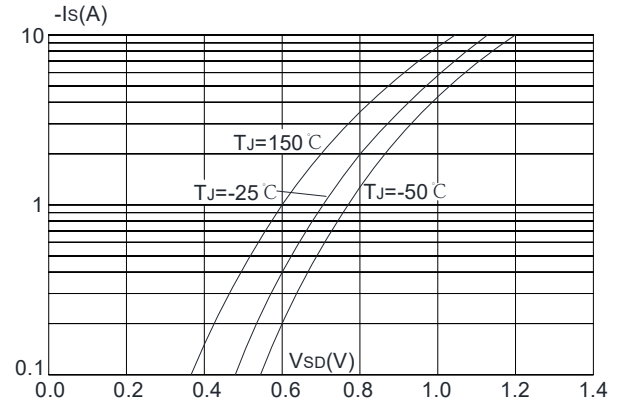
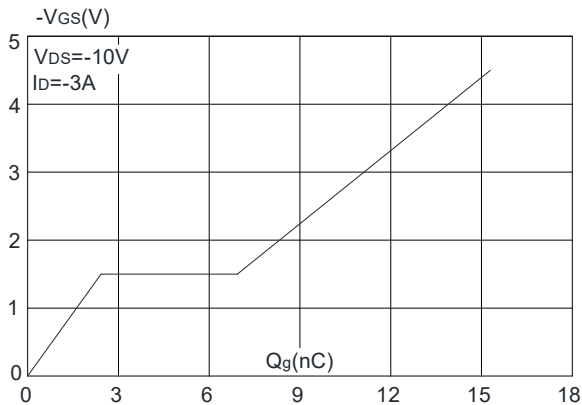
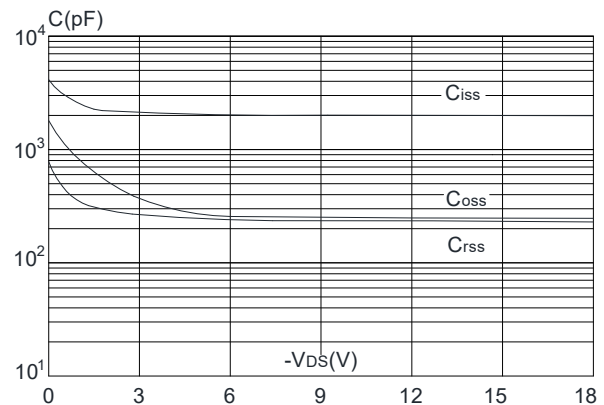
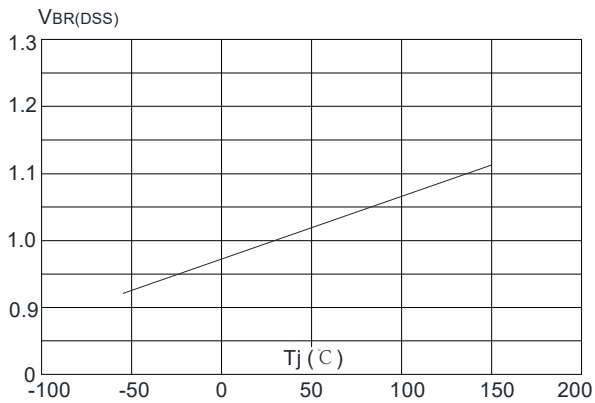
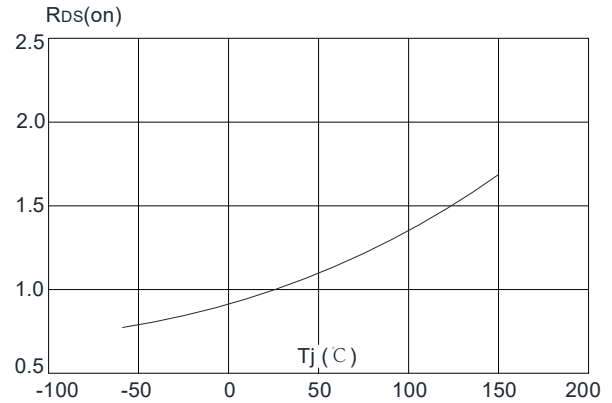
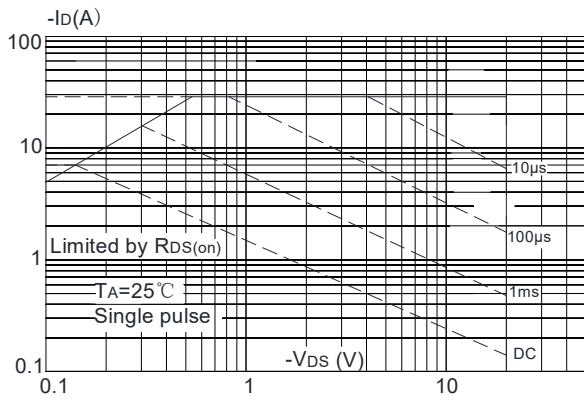
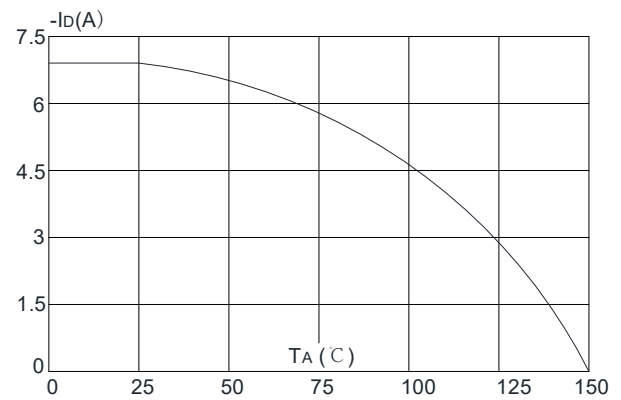
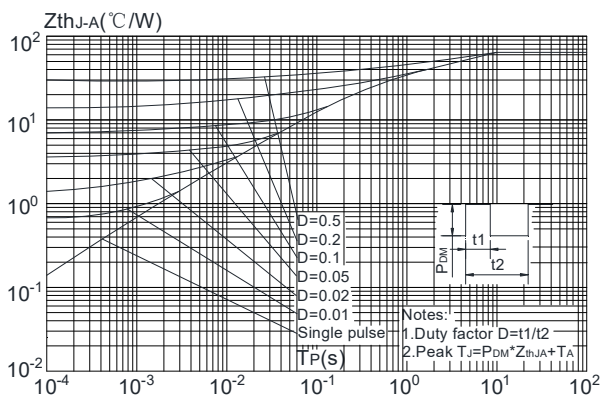
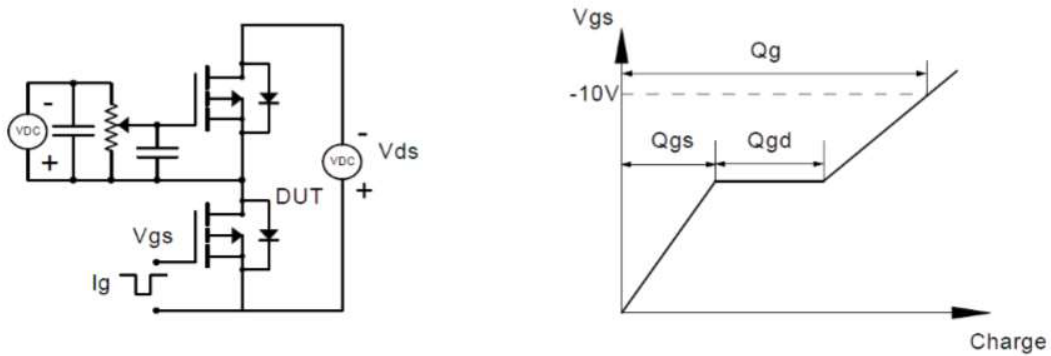
Figure1: Output Characteristics

Figure 2: Typical Transfer Characteristics

Figure 3: On-resistance vs. Drain Current

Figure 4: Body Diode Characteristics

Figure 5: Gate Charge Characteristics

Figure 6: Capacitance Characteristics


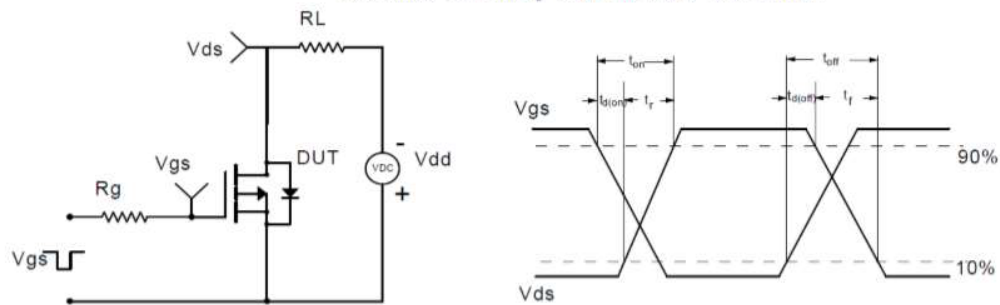
Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

Figure 8: Normalized on Resistance vs. Junction Temperature

Figure 9: Maximum Safe Operating Area

Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient


Test Circuit

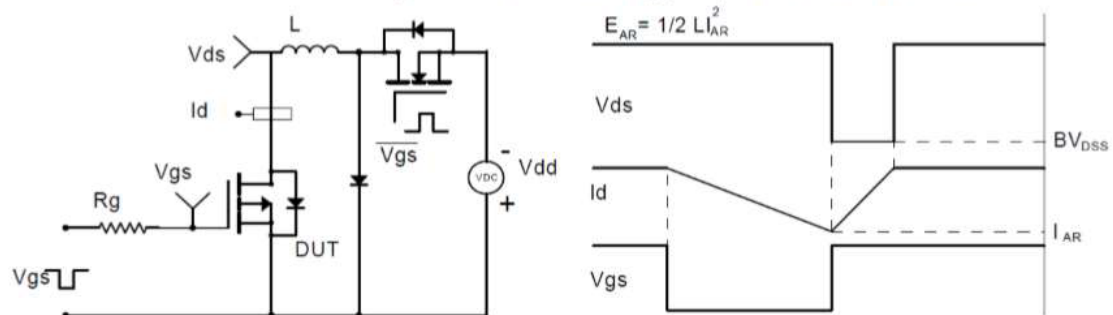
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

